

ABSTRACT

A method for manufacturing an electronic device includes at least a preparing step of preparing a structure (100) provided with an adhesive film (50) provided with a base material layer (10), an adhesive resin layer (A) provided on a first surface (10A) side of the base material layer (10) and used for temporarily fixing an electronic component (70), an adhesive resin layer (B) provided on a second surface (10B) side of the base material layer (10) and in which an adhesive force is reduced by external stimuli, and an unevenness-absorbing resin layer (C) provided between the base material layer (10) and the adhesive resin layer (A) or between the base material layer (10) and the adhesive resin layer (B), an electronic component (70) attached to the adhesive resin layer (A) of the adhesive film (50) and having an uneven structure (75), and a support substrate (80) attached to the adhesive resin layer (B) of the adhesive film (50); and a sealing step of sealing the electronic component (70) with a sealing material (60).